

## **MKD AC Film Capacitor**

## **Material Data Sheet**

Product Class	FilterCap MKD AC: B32371*, B32373* and B32376* series		Nagara yea	
Date	November 1st, 2019	0.0257 A4000.2010 at 10.000 at 10.00		Annual Control of the
IMDS ID if available		The state of the s	The second part and the second	The state of the s
Version	03	B32371	B32373	B32376

Product Part (IMDS: semi compor	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance			TMPS**) [wt%]	CAS if applicable	Typical mass of material [wt-%]	Traces see 1)	
Active Part	Polymer	2A	Polypropylene			100	9003-07-0	43.61		
	Heavy Metal	1C	Zn			100	7440-66-6	6.22		
			others*):			2				
Encapsulation	Polymer	2A	DMC			100	23165-19-7	6.1		
	Polymer	2A	PBT	100	100	26062-94-2	0.81			
	Paper, Cardboard	6D	Cellulose			100	9004-34-6	1.39		
	Polymer	2C	Polyurethane resin			100	9003-29-6	25.69		
	Light Metal	1B	Al			100	7429-90-5	18.56		
	Polymer	2A	PE			100	24937-78-8	0.1		
	Elastomer	2B	Silicon			100	7440-21-3	0.18		
Termination	Metal	1A	Steel			100	7439-89-6	1.48		
	Metal	1C	Brass			100	7440-31-5	15.41		
	Metal	1C	Sn			100	7440-31-5	0.5		
	Metal	1C	Copper		100 100	7440-50-8 7440-02-0	1.67 0.02			
	Metal	1C	Ni							
	I	I.	I				Sum in total:	100		
Sizes DxH [mm] Weight range [kg] 0.2-5.5						Part numbers: B32371X, B32373X, B32376X				
Not Part of a P	roduct Class	<u> </u>	I			1	ı			
Contact	Dennis Huang	nnis Huang			ortant rema	ırks:				
Division	TDK (Zhuhai FTZ) Co., Ltd	( (Zhuhai FTZ) Co., Ltd			1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are					
Address	No.4 Lianfeng Road, Xiangzhou District, 519030 Zhuhai City PR CHINA			product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.  2) This Material Data Sheet contains typical values of the respective products set forth						

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The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

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<sup>\*)</sup> others: .(not declarable or prohibited substances acc. GADSL)

<sup>\*\*)</sup> typical mass percentage of substance



RoHS - Exempt	tions for the Product Class / Product according to Annex III: ( 🗹 valid 🗅 not valid )
$\ \ \square$ no exemptions;	
☐ Exemption 6 (a):	Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
☐ Exemption 6 (b):	Lead as an alloying element in aluminum containing up to 0,4 % lead by weight;
☐ Exemption 6 (c):	Copper alloy containing up to 4 % lead by weight;
☐ Exemption 7 (a):	Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
☐ Exemption 7 (c)-I:	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
☐ Exemption 7 (c)-II:	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
☐ Exemption 7 (c)-III	: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
☐ Exemption 15:	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
☐ Other Exemption t	han above